

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
S127	8	S126 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 18:16
S128	3434	((438/108) or (438/116) or (438/123) or (438/124)).CCLS.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	OFF	2005/12/23 18:46
S129	2	"5869883".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 17:09
S130	217667	flip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 17:09
S131	0	S129 and S130	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 17:09
S132	27237	ball adj grid adj array bga ball-grid adj array	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 17:10
S133	31198	flip adj chip flip-chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 17:10
S134	66300	lead\$4 adj frame lead\$4-frame	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 17:12
S135	6565	premold\$5 pre adj mold\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:49

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S13 6	194	S135 same S134	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 17:12
S13 7	39	S136 and (S132 S133)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 17:13
S13 8	27	S137 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:34
S13 9	2	"20020047501".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 18:17
S14 0	242233	mosfet or (metal adj (oxide insulat\$4) adj semiconductor adj (fet or field)) or pmos or cmos or nmos or misfet	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 18:17
S14 1	4594	verti\$8 near S140 vmosfet vmos vcmos v?mos\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 18:17
S14 2	0	S139 and (S140 S141)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 18:17
S14 3	14521	source near2 lead	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 18:29
S14 4	24353	gate near2 (lead wire wiring)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 18:30
S14 5	41025	source near2 (lead wire wiring pad ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 18:31

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S14 6	31054	gate near2 (lead wire wiring pad ball)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 18:31
S14 7	25	S141 and S145 and S146 and S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 18:31
S14 8	8	S147 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:23
S14 9	0	S139 and (reflow\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:25
S15 0	2	"6392290".pn.	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:25
S15 1	1	S150 and (reflow\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:26
S15 2	2	S150 and (solder ball bump reflow\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:41
S15 3	1	S150 and (solder ball bump reflow\$4) same (heat\$4 thermal\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:33
S15 4	9	S133 with S134 with (reflow\$4)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:34
S15 5	6	S154 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:41

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S15 6	6	(solder ball bump) with reflow\$4 with S134 with S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:42
S15 7	4	S156 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:42
S15 8	7	(solder ball bump) near4 S134 with reflow\$4 same S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:54
S15 9	5	S158 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:58
S16 0	270	(solder ball bump) near2 (form\$4 attach\$4 deposit\$4) near2 S134	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:56
S16 1	1613572	ic die dice chip	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:55
S16 2	6700	(solder ball bump) near2 (form\$4 attach\$4 deposit\$4) near2 S161	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:56
S16 3	2626	S161 and S162 and reflow\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:56
S16 4	1028	S161 same S162 same reflow\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:57
S16 5	186	(solder ball bump) near2 (form\$4 deposit\$4) near2 S134	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:15

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S16 6	4979	(solder ball bump) near2 (form\$4 deposit\$4) near2 S161	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:15
S16 7	0	S165 same S166 same reflow\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:58
S16 8	9	S165 and S166 and reflow\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 19:58
S16 9	6	S168 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:04
S17 0	31204	S165 same reflow\$4 S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:03
S17 1	0	S165 with reflow\$4 with S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:03
S17 2	0	S165 with reflow\$4 same S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:04
S17 3	0	S165 with reflow\$4 and S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:03
S17 4	1851	(solder ball bump) with (form\$4 deposit\$4) with S134	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:04
S17 5	7	S174 with reflow\$4 same S133	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:04

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S17 6	5	S175 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:16
S17 7	2776	(solder ball bump) near2 (form\$4 deposit\$4) near2 (S134 board pcb)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:15
S17 8	201	S177 same S174	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:16
S17 9	13	S177 same S174 same reflow\$4	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:16
S18 0	3	S179 and (@ad < "20030211")	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:16
S18 1	6565	pre mold\$5 pre adj mold\$5	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:49
S18 2	1	S139 and S135	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/04/10 20:49